

Abstract

Improvements Relating to Electronic Circuit Packages

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This invention relates to electronic circuit packages designed to hold high frequency circuits operating particularly, but not exclusively, in the microwave, millimetre wave, and sub-millimetre wave bands. The invention provides a package incorporating a cavity in a material for containment of the circuits,

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wherein the package further incorporates at least one conductive surface mounted on an inner surface extending into the cavity, the conductivity thereof being adapted to be at least partially absorbent to electromagnetic radiation.

The conductive surface according to the present invention will tend to attenuate electromagnetic radiation present within the cavity, and so help to

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prevent undesired coupling from one point to another within the cavity. The conductivity of the conductive material is preferably arranged to match the impedance of the radiation mode estimated or computed to be present within the cavity.

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(Figure 3)